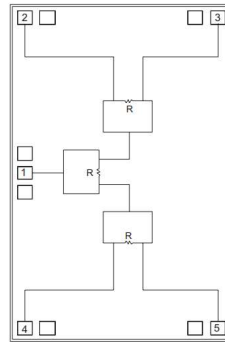


Performance

- Frequency: 22~32GHz
- Insertion loss: 0.8dB
- Chip size: 2.00*0.90*0.1mm

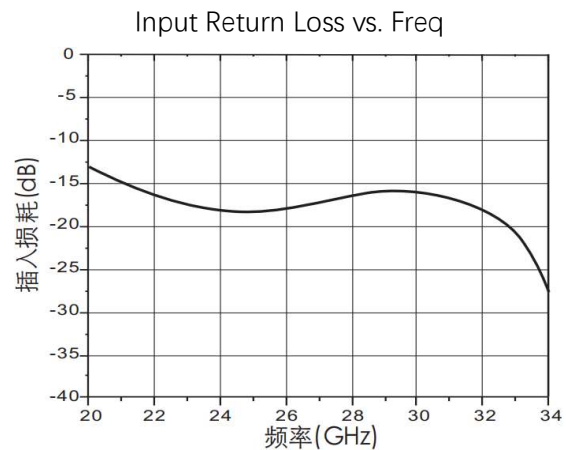
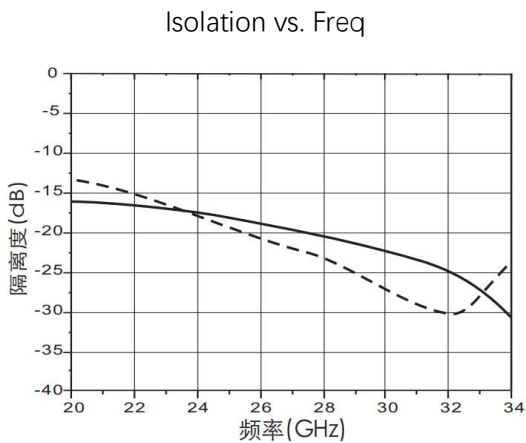
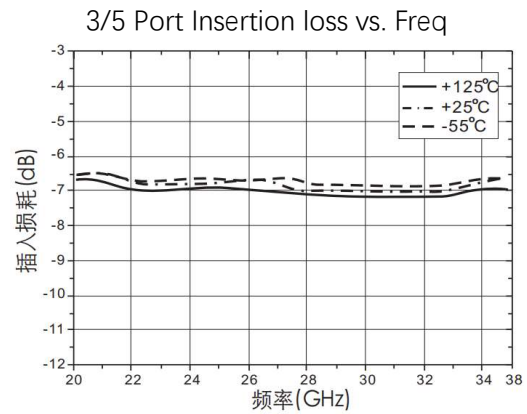
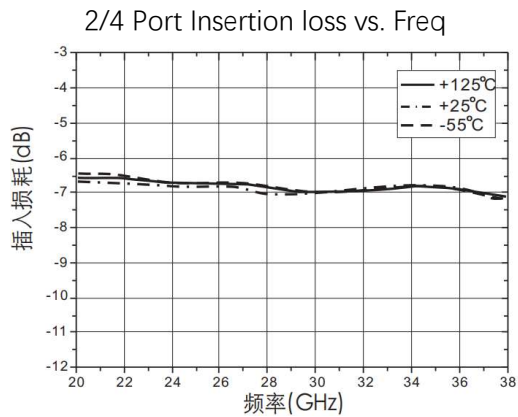
Function Diagram

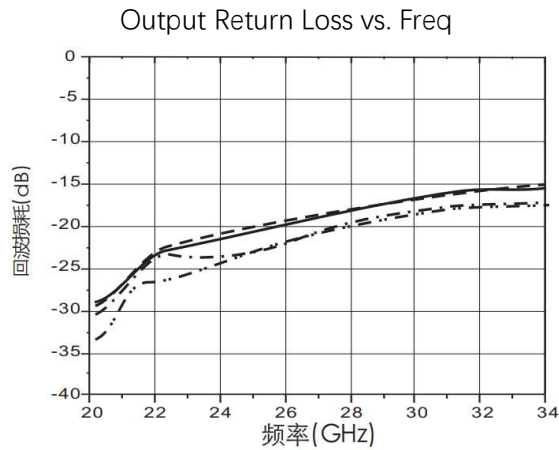


Electrical Specifications (Ta=+25°C, 50Ω system)

Parameter	Min	Typical	Max	Unit
Frequency Range	22~32			GHz
Insertion Loss	-	0.8	1.0	dB
Insertion Loss Ripple	-	±0.3	-	dB
Isolation	15	17	-	dB
Input Return Loss	16	18	-	dB
Output Return Loss	16	18	-	dB

Test Curves

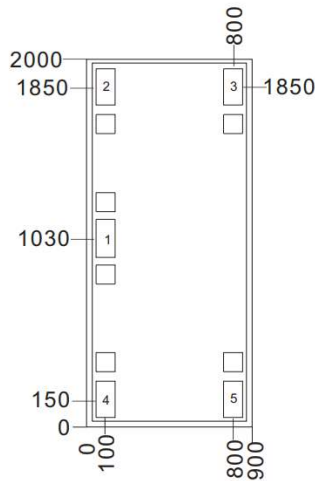




Absolute Max Ratings

Parameter	Value
Input Signal Power	+33dBm
Storage Temperature	-65~150°C
Operating Temperature	-55~125°C
Static protection Grade (HBM)	Class 1C

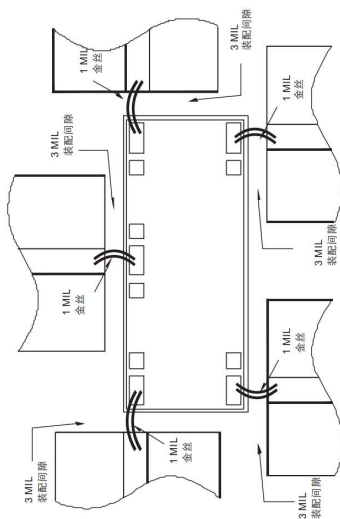
Outline Size



Note:

1. Unit: um
2. Bottom side is gold plated
3. Bottom side is GND
4. Bonding pads is gold plated
Pads size: 200*100 um
5. Don't bonding on thru holds
6. Tolerance: ±50um

Assembly Diagram



Bonding Definition

No.	Number	Description
1	IN	RF input, 50ohm
2,3,4,5	Out1,Out2,Out3,Out4	RF output, 50ohm
	GND	Bottom must be grounded